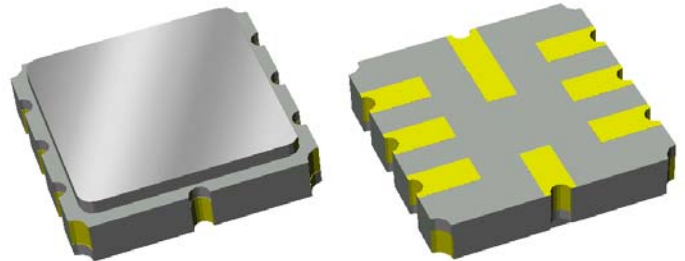


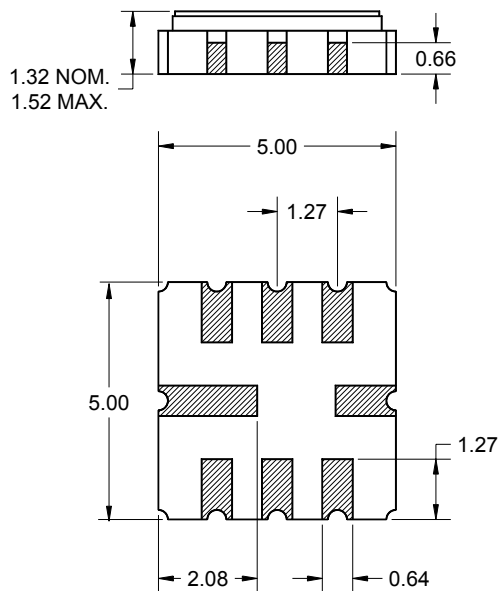
Features

- For WCDMA applications
- Usable bandwidth of 5 MHz
- Low loss
- Single-ended operation
- Ceramic Surface Mount Package (SMP)
- Small size



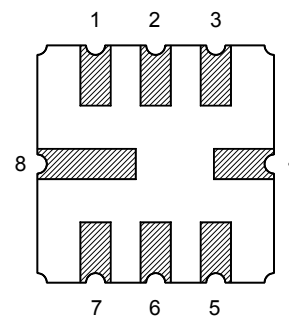
Package

Surface Mount 5.00 x 5.00 x 1.32 mm



Pin Configuration

Bottom View



Pin No.	Description
2	Input
3	Input return
6	Output
7	Output return
1,4,5,8	Case ground

Dimensions shown are nominal in millimeters
All tolerances are ± 0.15 mm except overall
length and width $\pm 0.15/\pm 0.10$ mm

Body: Al_2O_3 ceramic
Lid: Kovar, Ni plated
Terminations: Au plating 0.5 - 1.0 μ m,
over a 2 - 6 μ m Ni plating

Electrical Specifications ⁽¹⁾

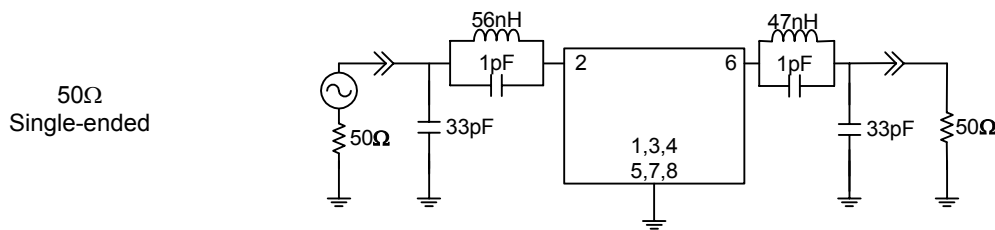
Operating Temperature Range: ⁽²⁾ -30 to +70 °C

Parameter ⁽³⁾	Minimum	Typical	Maximum	Unit
Center Frequency, f_0	-	190	-	MHz
Insertion Loss at 190 MHz	-	8	10	dB
Lower 5 dB Bandedge ⁽⁴⁾	-	187.23	187.6	MHz
Upper 5 dB Bandedge	192.4	193.01	-	MHz
Phase Ripple 188 - 192 MHz	-	1.90	4.15	deg RMS
Attenuation ⁽⁴⁾				
160 - 170 MHz	33	39.9	-	dB
170 - 180 MHz	27	35.4	-	dB
180 - 185.5 MHz	25	30.3	-	dB
194.5 - 200 MHz	25	29.5	-	dB
200 - 210 MHz	27	34.9	-	dB
210 - 220 MHz	33	42.7	-	dB
Source Impedance ⁽⁵⁾	-	50	-	Ω
Load Impedance ⁽⁵⁾	-	50	-	Ω
Substrate Material	-	LiTaO ₃		

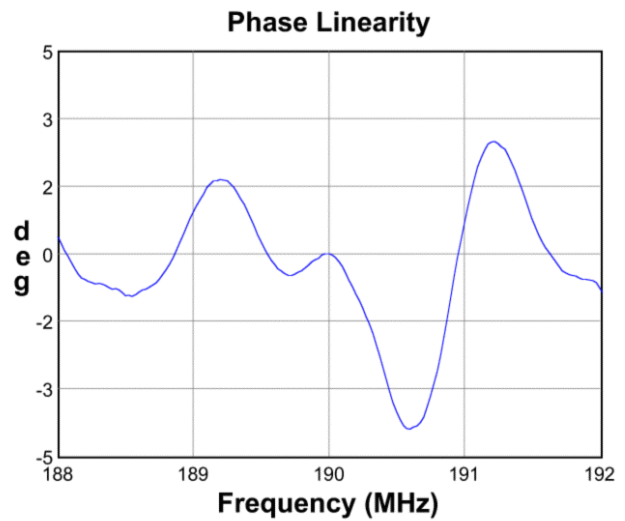
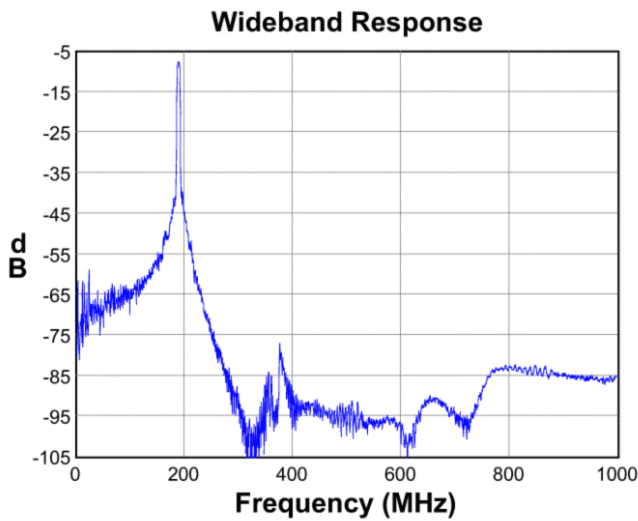
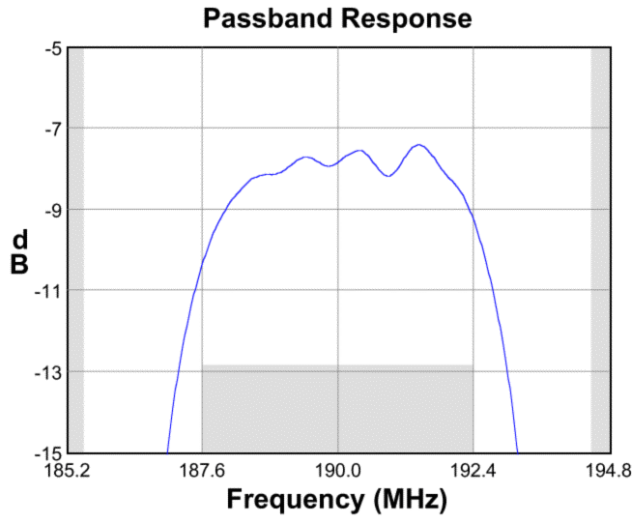
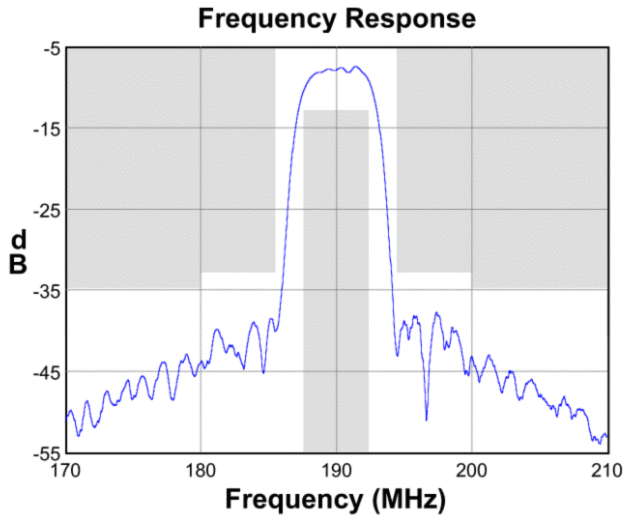
Notes:

1. All specifications are based on the test circuit shown below
2. In production, devices will be tested at room temperature to a guardbanded specification to ensure electrical compliance over temperature
3. Electrical margin has been built into the design to account for the variations due to temperature drift and manufacturing tolerances
4. Relative to insertion loss at 190 MHz
5. This is the optimum impedance in order to achieve the performance shown

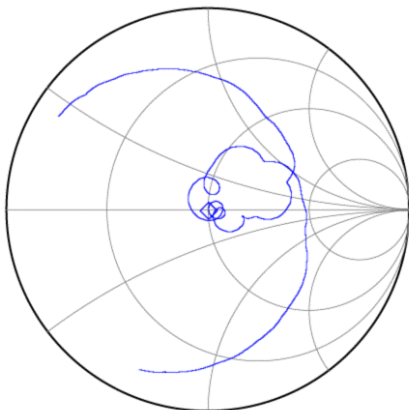
Test Circuit:



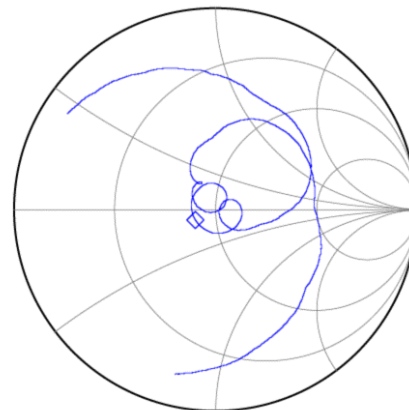
Typical Performance (at +25°C)



Input Smith Chart

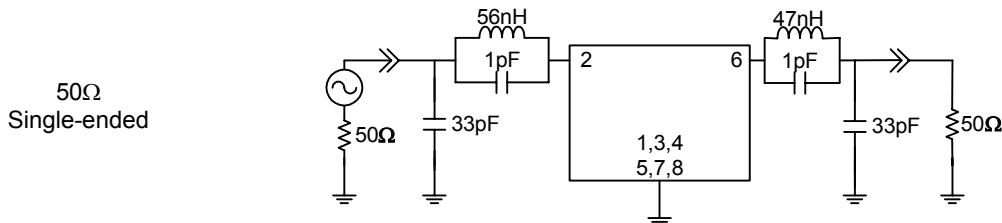


Output Smith Chart

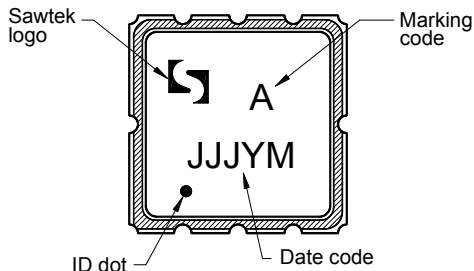


Matching Schematics

Actual matching values may vary due to PCB layout and parasitics

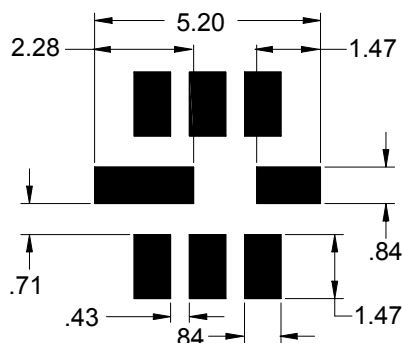


Marking



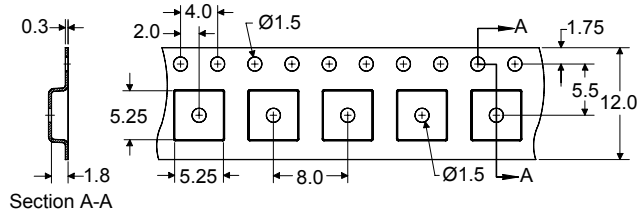
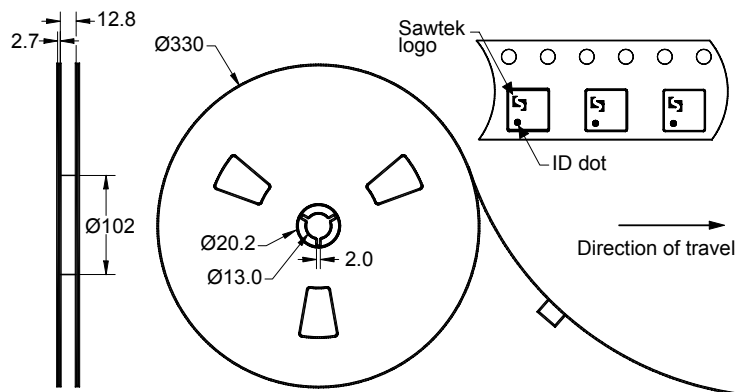
The date code consists of: JJJ = Julian day,
Y = last digit of year, M = manufacturing site code

PCB Footprint



This footprint represents a recommendation only
Dimensions shown are nominal in millimeters

Tape and Reel




Dimensions shown are nominal in millimeters
Packaging quantity: 4000 units/reel

Maximum Ratings


Parameter	Symbol	Minimum	Maximum	Unit
Operating Temperature Range	T	-30	+70	°C
Storage Temperature Range	T _{stg}	-40	+85	°C

Important Notes

Warnings

- Electrostatic Sensitive Device (ESD) 
- Avoid ultrasonic exposure

RoHS Compliance

- This product complies with EU directive 2002/95/EC (RoHS) 

Solderability

- Compatible with JEDEC J-STD-020C **Pb**-free process, **260°C** peak reflow temperature ([see soldering profile](#))

Links to Additional Technical Information

[PCB Layout Tips](#)

[Qualification Flowchart](#)

[Soldering Profile](#)

[S-Parameters](#)

[RoHS Information](#)

[Other Technical Information](#)

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